

Low Dk material for Test Sockets

TZ3300-L Series

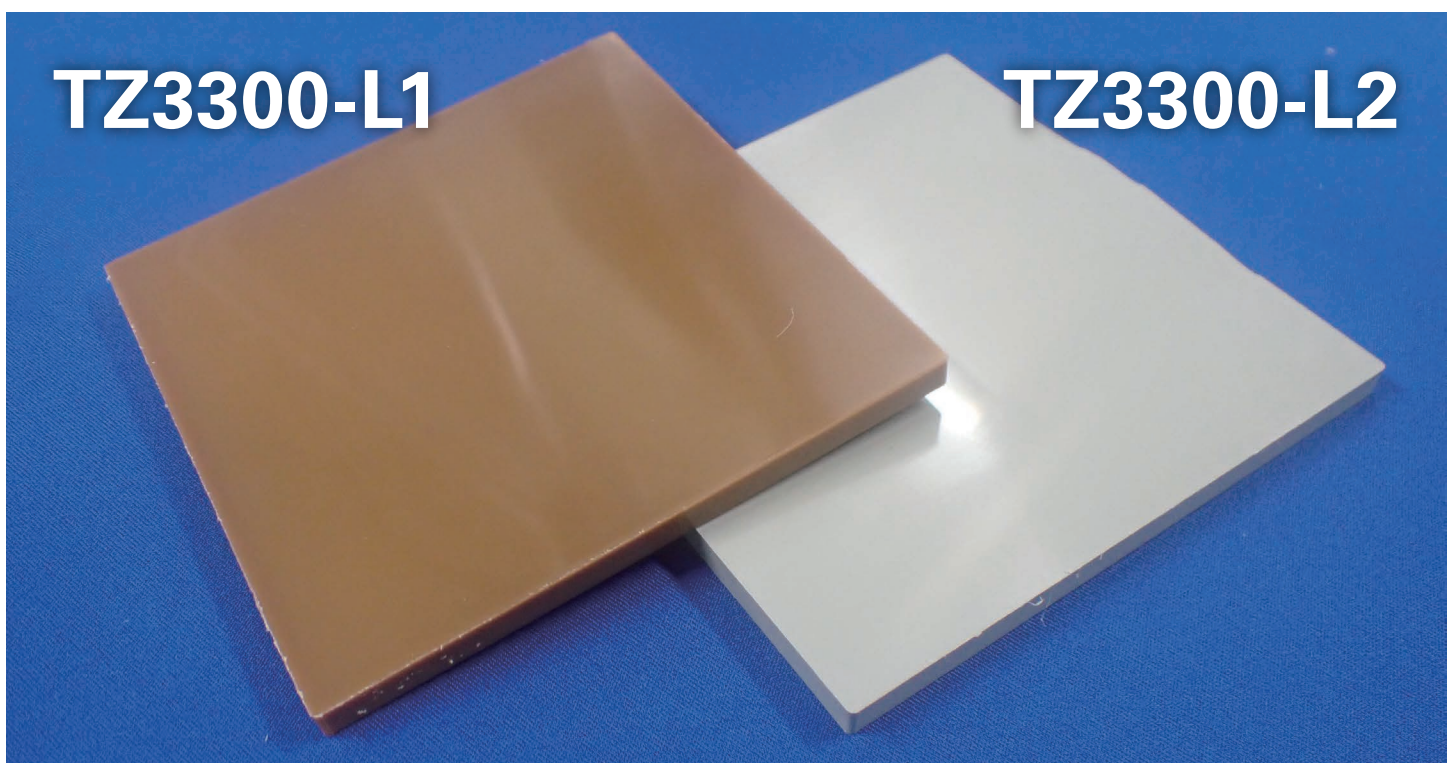
MGC

Ceramic reinforced PI material

Next-Generation Substrate for IC Testing : Unparalleled Low Dk

Characteristic

- **Dk ≒ 2.6 (10GHz) - Among the Lowest in the Industry.**
- **Sub-100μm Precision Micromachining Capability.**
- **Superior Dimensional Stability with High-Temperature Resistant PI.**
- **Superior Machinability:Versatile Shaping for Diverse Applications**
- **PI Material with Exceptional Low Moisture Absorption**



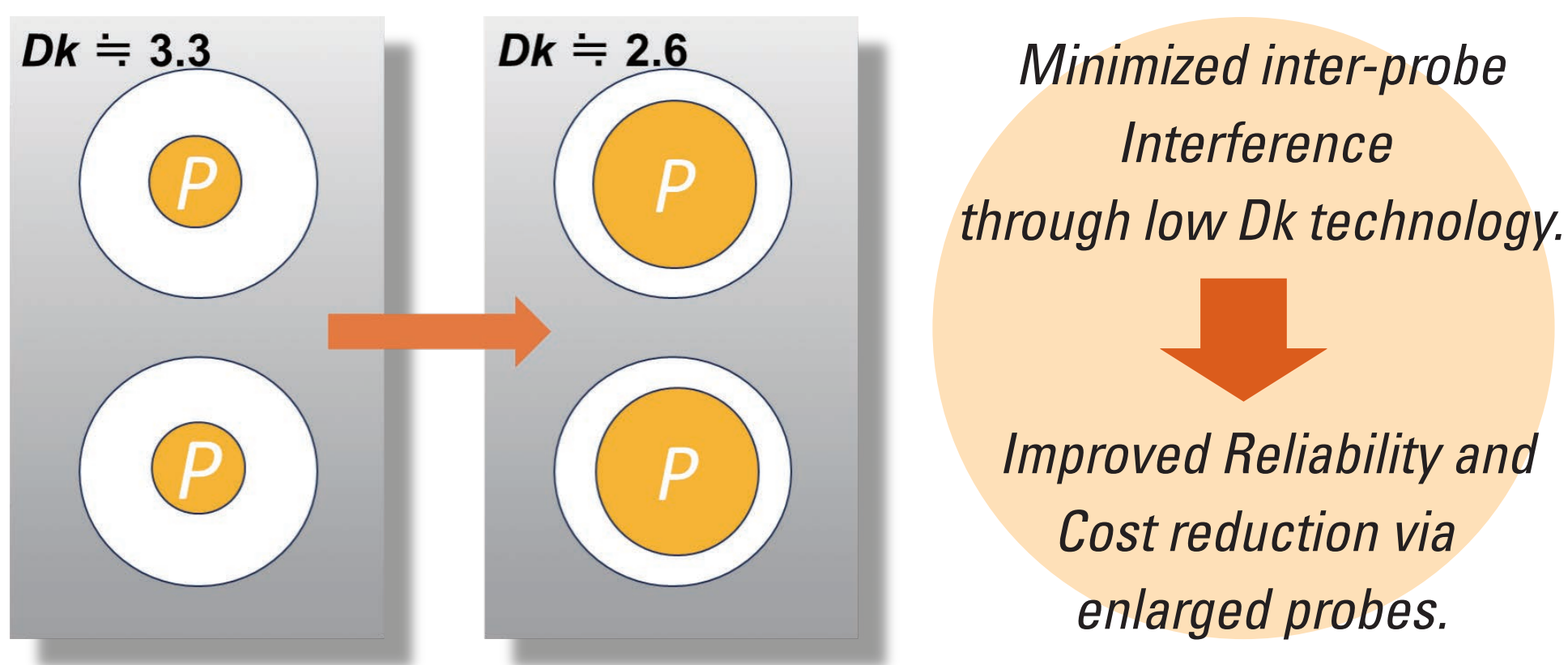
Basic Properties

Material properties

	Condition	Unit	L1	L2
Flexural strength	–	MPa	125	124
Flexural modulus	–	GPa	2.8	3.2
Dk	10GHz	–	2.67	2.67
Df	10GHz	–	0.0028	0.0035
CTI	–	V	≥600	550
Water absorption	24h immersion	%	0.1	0.1

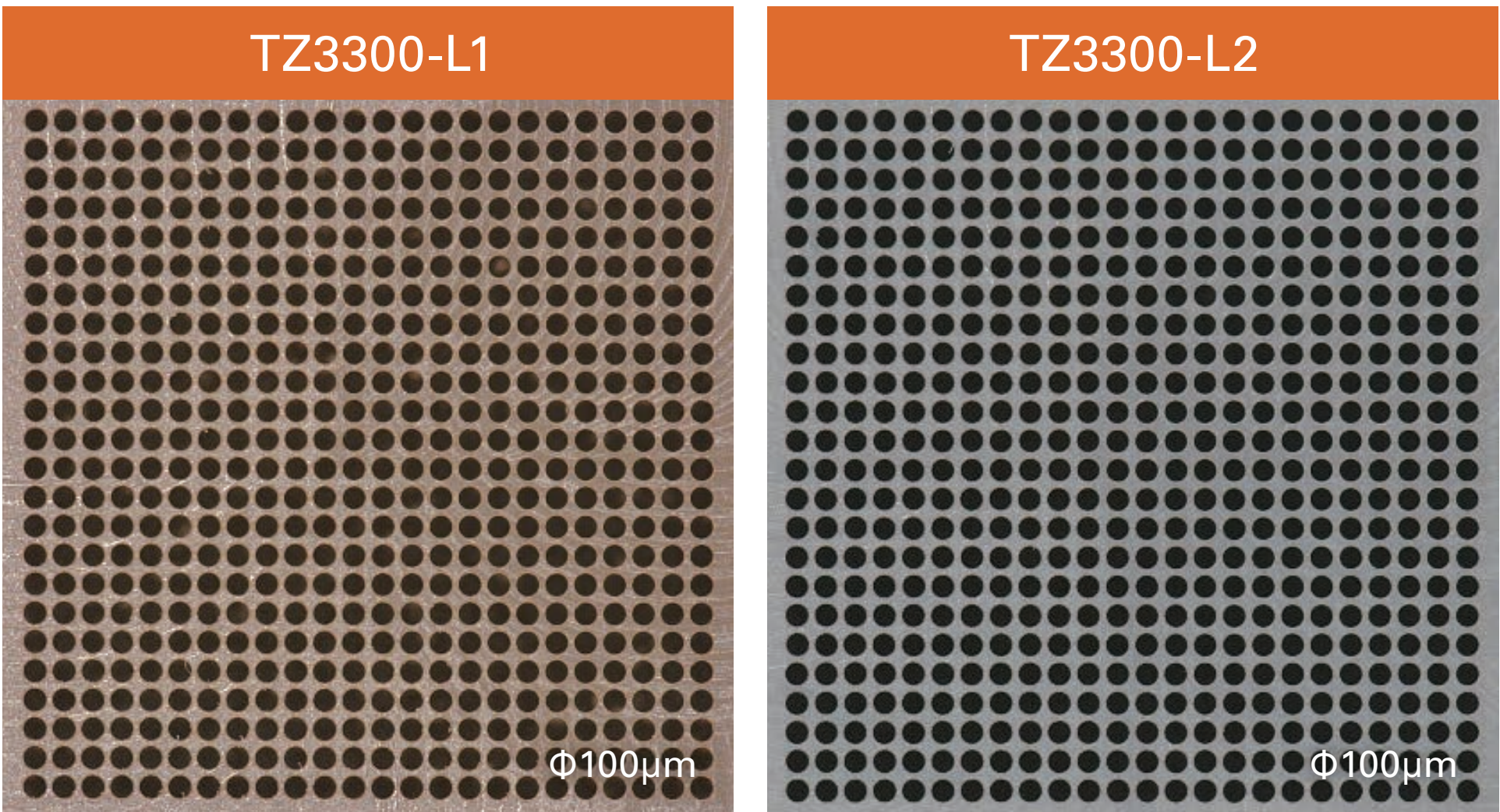
Industry Solutions

- **Enlarged Probe Diameter**



- **Miniaturization through High-Density Hole and Probe Design**

Drilling processability



No wall breakdown between holes    Clean, precise patterning with minimal burrs

Hole Diameter Distribution

